

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	26664	barrier same (ru re)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 18:16
L2	6633	barrier with (ru re)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 18:27
L3	1123	2 with (prevent preventing prevented diffusion diffused diffusing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 18:30
L4	469	(semiconductor component ic (integrated adj circuit) device die chip dice) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 18:30
L5	46	4 same (cupper cu)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 18:31
L6	7250	barrier with (ru ruthenium rhenium re)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 18:28
L7	1379	6 with (prevent preventing prevented diffusion diffused diffusing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 18:30
L8	554	(semiconductor component ic (integrated adj circuit) device die chip dice) same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 18:30

L9	90	8 same (copper cu)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 18:31
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